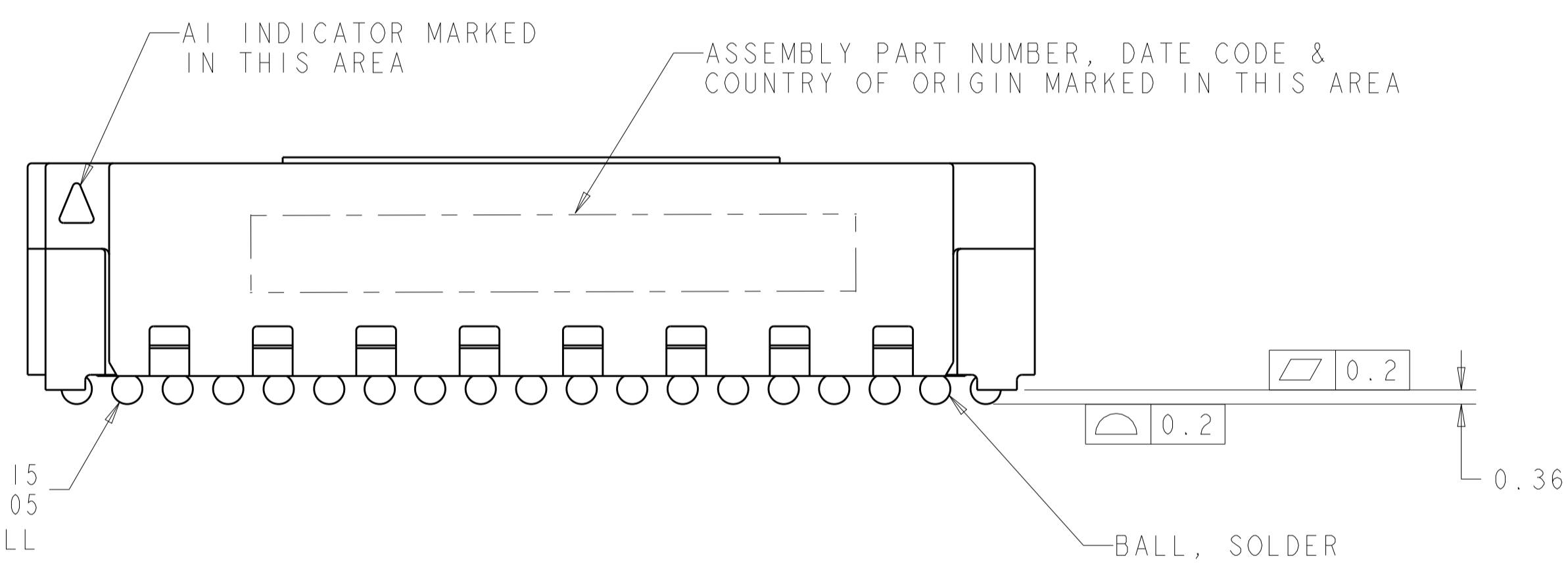
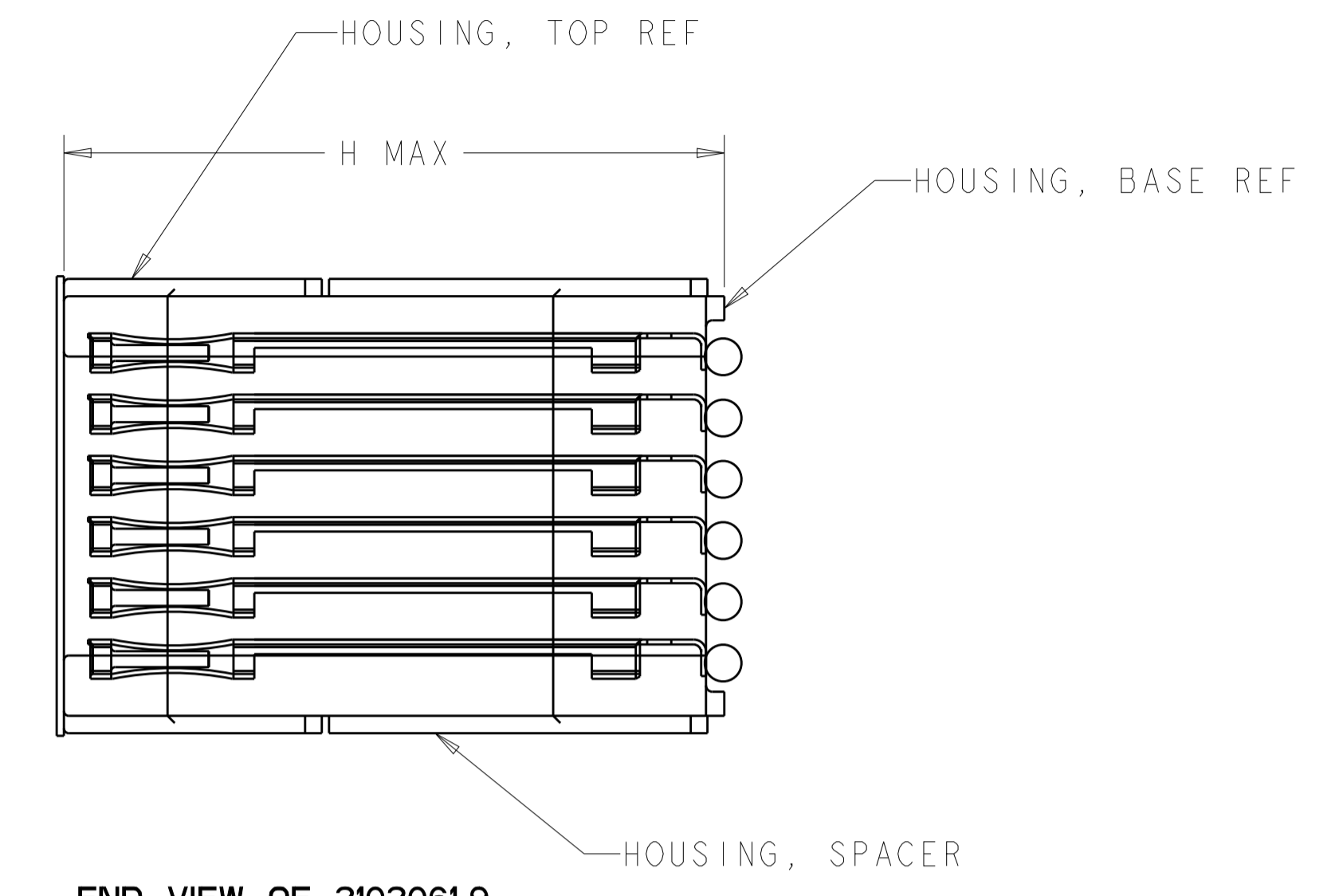
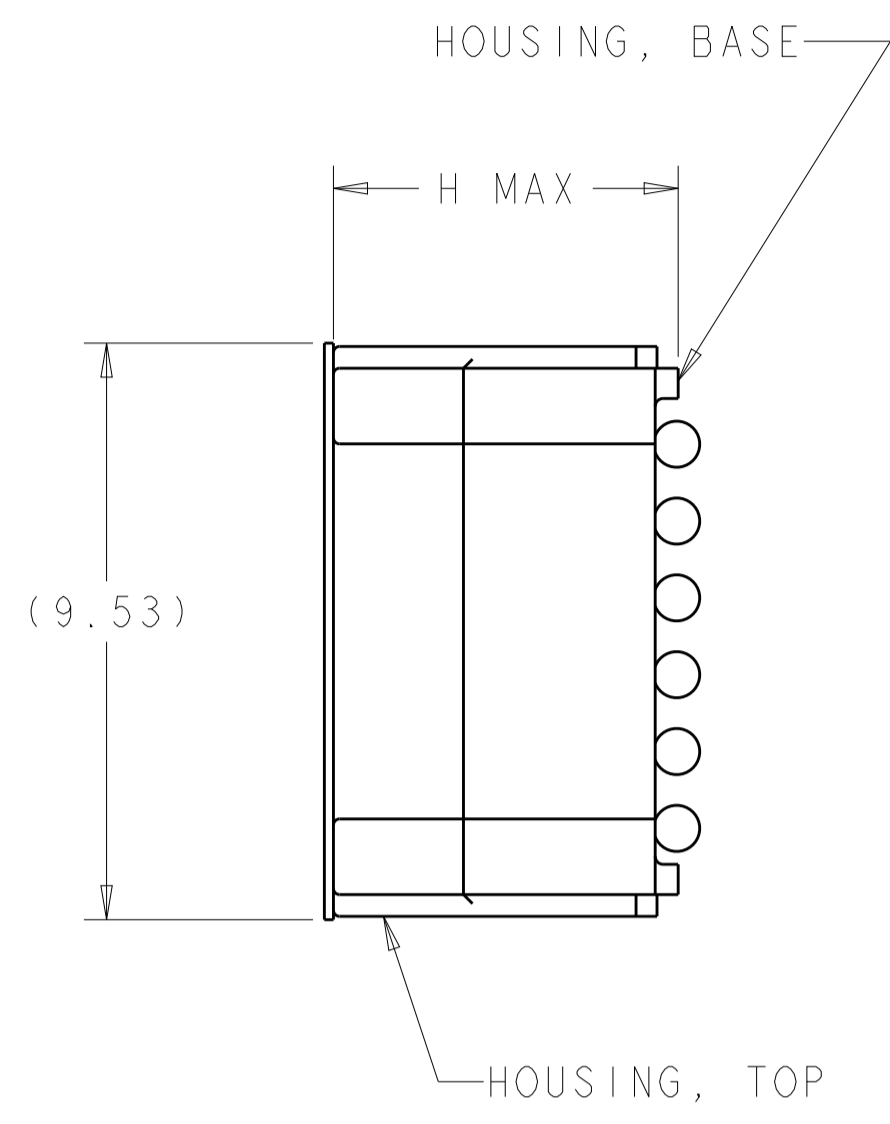
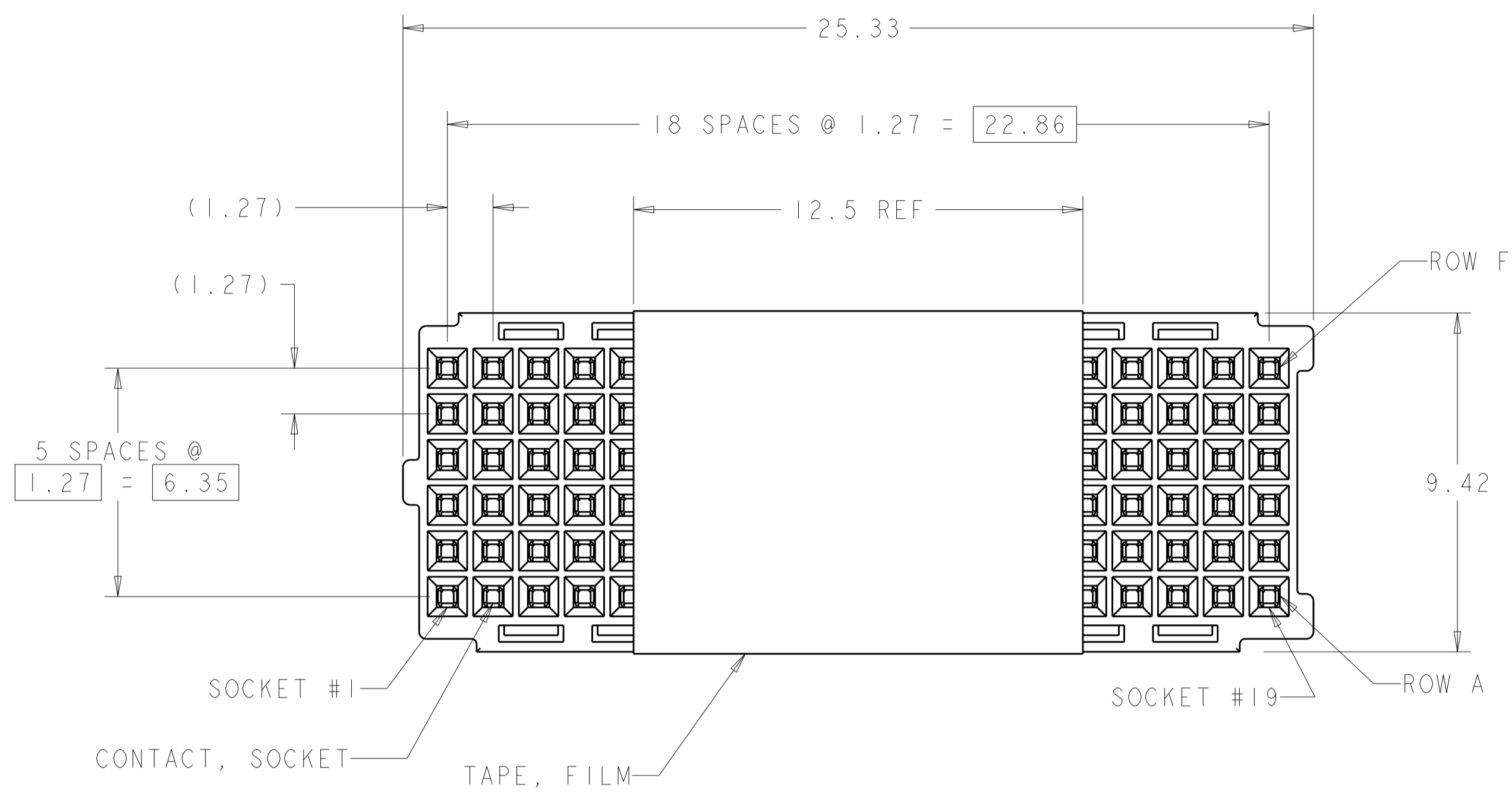


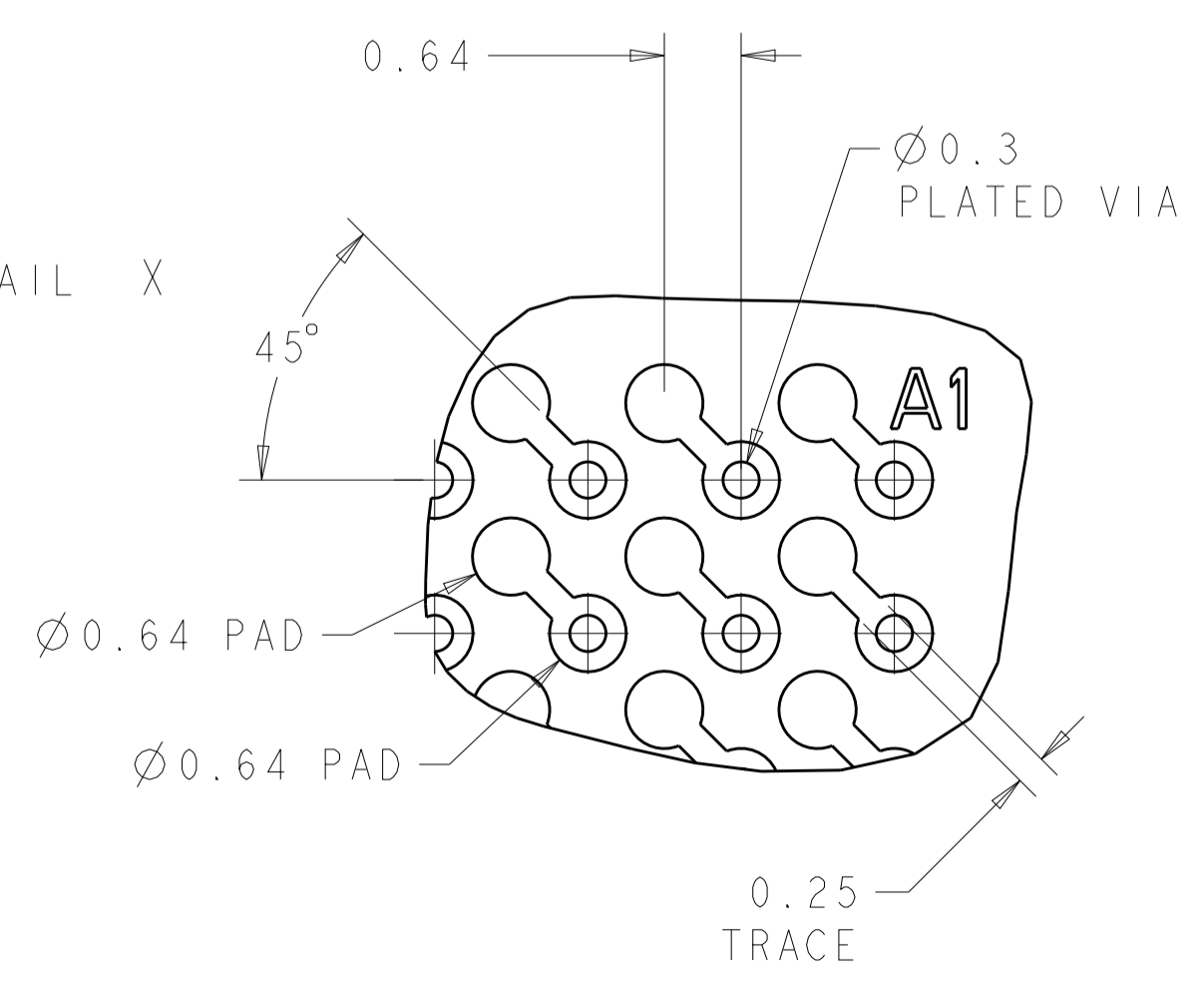
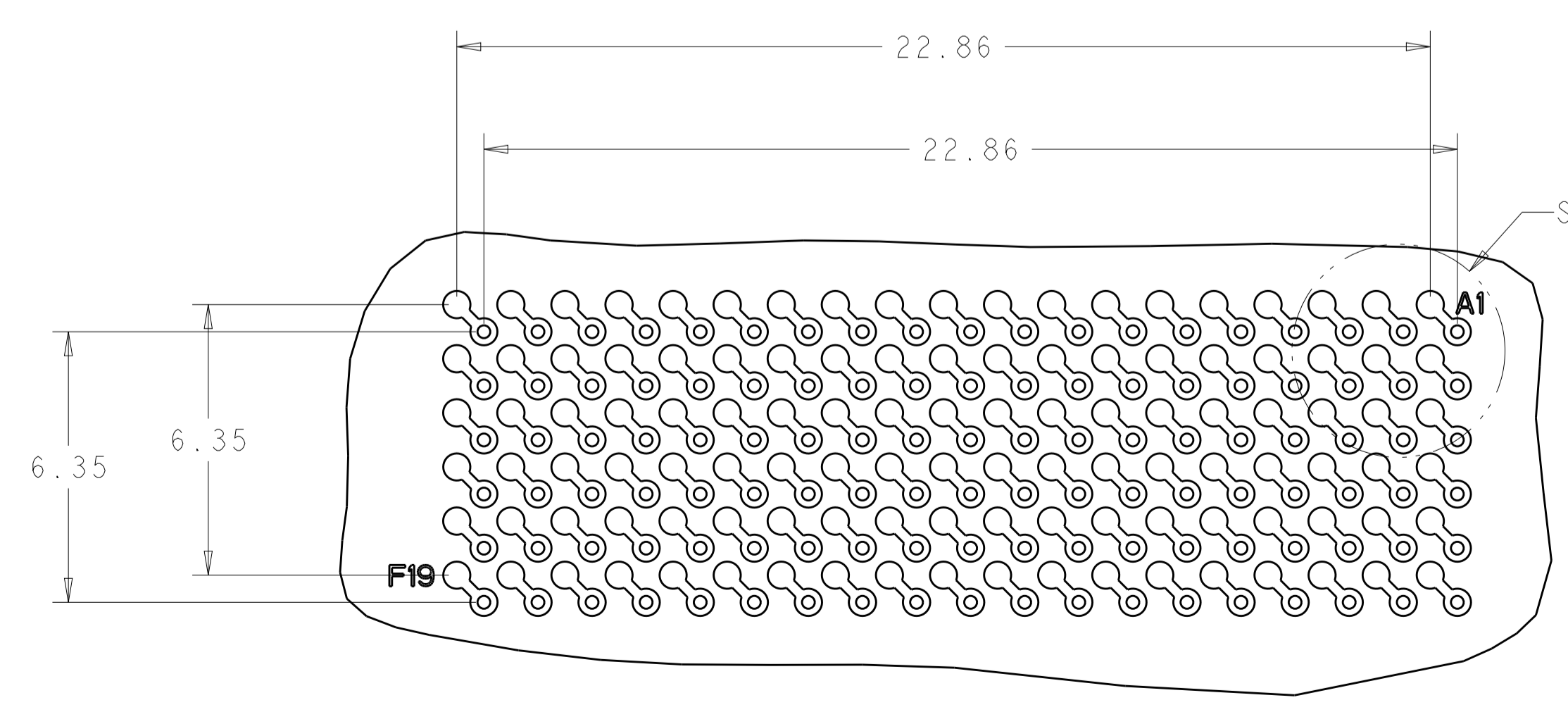
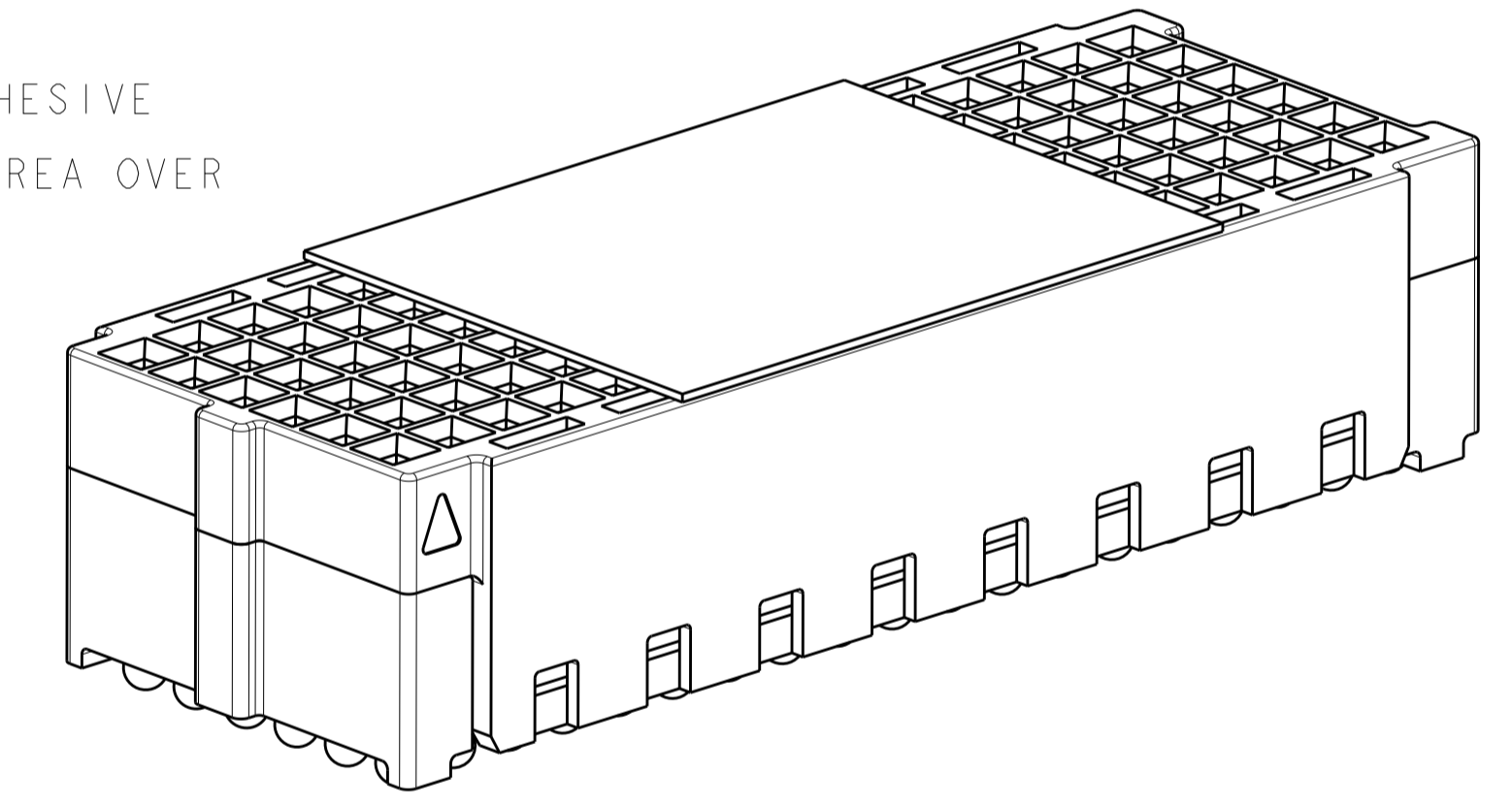
LOC	DIST	REVISIONS			
		REV	DESCRIPTION	DATE	BY
		F	REV PER ECO 12-021576	12-18-12	CT DH
		G	REV. PER ECO-13-005882	05APR2013	RJM3 DH



△ MATERIAL: HOUSINGS; LCP, COLOR-NATURAL
CONTACT; BERYLLIUM COPPER
SOLDER BALL; SEE TABLE
TAPE, FILM; KAPTON WITH SILICON ADHESIVE

△ FINISH: CONTACT; GOLD (SEE TABLE) ON MATING AREA OVER
NICKEL ON ENTIRE CONTACT.

3. PRODUCT IS PACKAGED ON TAPE AND REELED.



MATING PART NUMBER	MATED STACK HEIGHT (mm)	GOLD PLATING THICKNESS	H MAX REF	SOLDER BALL MATERIAL	PART NUMBER
2102060-4	15	0.76 μm	11	LEAD FREE PER SAC405	1-2102061-6
2102060-3	15	0.76 μm	11	TIN LEAD	1-2102061-5
2102060-2	15	1.27 μm	11	LEAD FREE PER SAC405	1-2102061-4
2102060-1	15	1.27 μm	11	TIN LEAD	1-2102061-3
2102060-4	8	0.76 μm	14	LEAD FREE PER SAC405	1-2102061-2
2102060-3	8	0.76 μm	14	TIN LEAD	1-2102061-1
2102060-2	18	1.27 μm	14	LEAD FREE PER SAC405	1-2102061-0
2102060-1	18	1.27 μm	14	TIN LEAD	2102061-9
2102060-4	12	0.76 μm	8	LEAD FREE PER SAC405	2102061-8
2102060-3	12	0.76 μm	8	TIN LEAD	2102061-7
2102060-4	10	0.76 μm	6	LEAD FREE PER SAC405	2102061-6
2102060-3	10	0.76 μm	6	TIN LEAD	2102061-5
2102060-2	12	1.27 μm	8	LEAD FREE PER SAC405	2102061-4
2102060-1	12	1.27 μm	8	TIN LEAD	2102061-3
2102060-2	10	1.27 μm	6	LEAD FREE PER SAC405	2102061-2
2102060-1	10	1.27 μm	6	TIN LEAD	2102061-1

PCB LAYOUT (CONNECTOR SIDE)
SCALE 8:1

THIS DRAWING IS A CONTROLLED DOCUMENT. DWG: G. DOWDY 23JUL2009
CHK: K. DOWHOWER 23JUL2009
APP'D: K. DOWHOWER 23JUL2009

DIMENSIONS: mm
TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ±
1 PLC ±0.13
2 PLC ±
3 PLC ±
4 PLC ±
ANGLES ±

MATERIAL: FINISH: △

Customer Drawing

TE Connectivity
NAME: ASSEMBLY, SOCKET, 114 POSITION, MEZALOK STACKING CONNECTOR
SIZE: 108-2411
APPLICATION SPEC: 114-13279
WEIGHT: A100779
SCALE: 8:1 SHEET 1 OF 1 REV G